

# LDO - Week 1

## Previously:

- Continued working on the layouts of the OTA and the BGR.
- OTA layout mostly passes LVS but still has many unresolved DRC issues due to missing required layers (DOD, DPO, dummy metal layers).
- Additional DRC warnings related to flip chip packaging with Polyimide and a missing Sealing.

## This Week:

- Meeting with Tal to discuss the DRC issues.